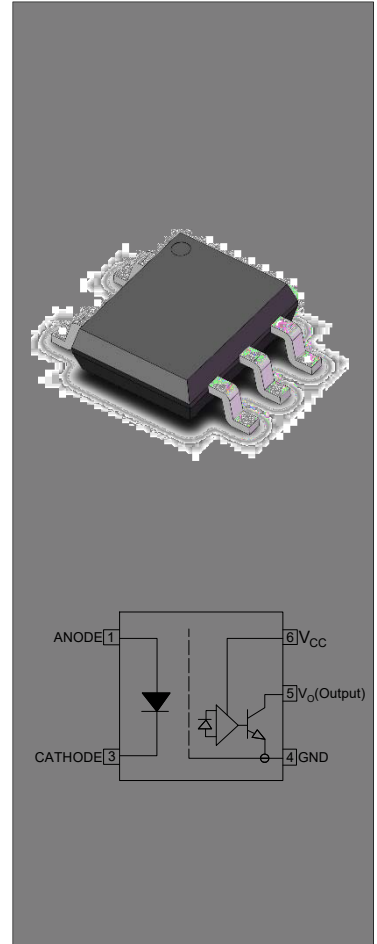




DESCRIPTION:

ollers, industrial inverters and switching



MAIN FEATURES

High isolation 3750 VRMS

High speed – 2MBd typical

Operating temperature range -55°C to 110°C

REACH & RoHS compliance

HBM: H3A; MM: M4; CDM: C3

CQC approved

VDE approved

UL approved

Truth Table

LED	Output
ON	L
OFF	H

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I _F	50	mA
	Peak Forward Current	I _{FP}	1	A
	Reverse Voltage	V _R	6	V
	Input Power Dissipation	P _D	100	mW
Output	Supply Voltage	V _{CC}	35	V
	Output Voltage	V _O	20	V

	Output Current	I_o	8	mA
	Output Power Dissipation	P_o	100	mW
Total Power Dissipation		P_{tot}	200	mW
Isolation Voltage		V_{iso}	3750	Vrms
Operating Temperature		T_{opr}	-55~110	
Junction Temperature		T_j	125	
Storage Temperature		T_{stg}	-55~125	
Soldering Temperature		T_{sol}	260	

NOTE1 100μs pulse, 100Hz frequency

NOTE2 AC for 1minute, R.H.=40~60%

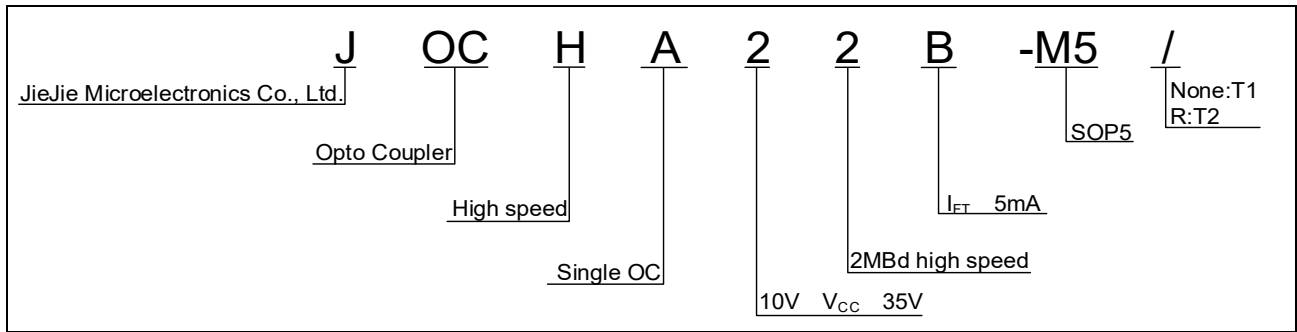
ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
-----------	--------	-----------	------	------	------	------

j bh

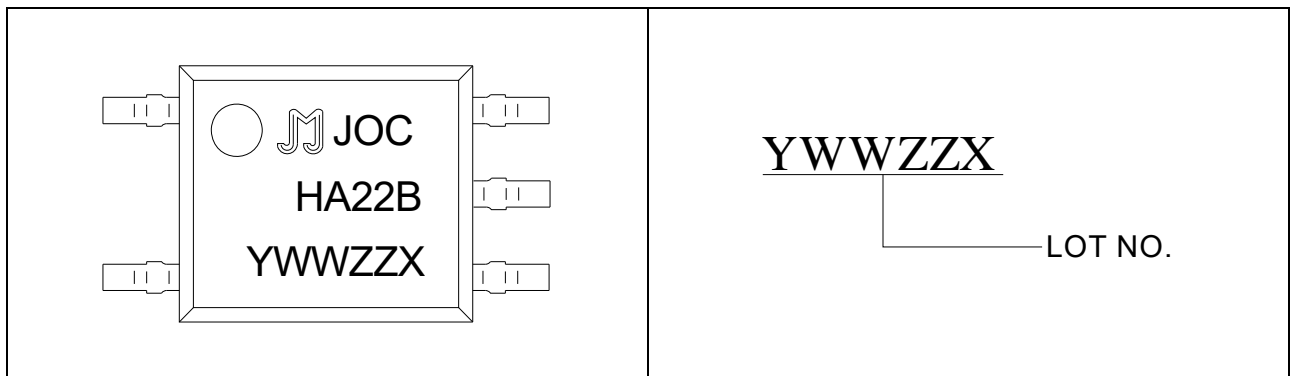
			$I_F=0$ 10mA, $R_L=20k\Omega$, $C_L=10pF$	-	70	-	ns
Propagation Delay Time to Logic High	TPLH		$I_F=10$ 0mA, $R_L=20k\Omega$, $C_L=100pF$	150	350	550	ns
			$I_F=10$ 0mA, $R_L=20k\Omega$, $C_L=10pF$	-	110	-	ns
Common Mode Transient Immunity at Logic High	CM _H		$I_F=0mA$, $V_{CM}=1500Vpp$, $R_L=20k\Omega$	± 20	± 25	-	kV/ μs
Common Mode Transient Immunity at Logic Low	CM _L		$I_F=10mA$, $V_{CM}=1500Vpp$, $R_L=20k\Omega$	± 20	± 25	-	kV/ μs

ORDERING INFORMATION



Packing Quantity	
Option	Quantity
None/R	3000 Units/Reel

MARKING



Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

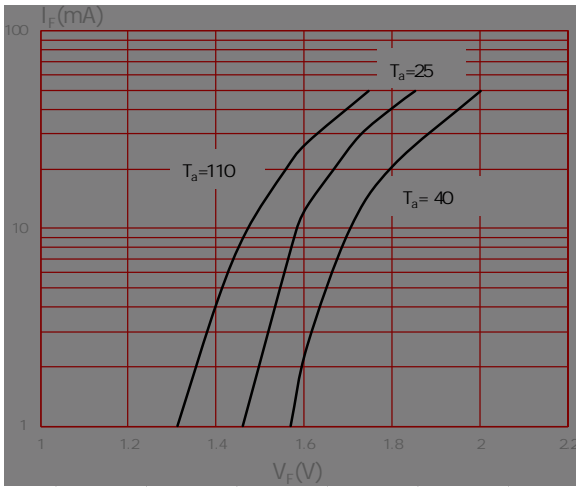


FIG.3: Output Current vs. Forward Current

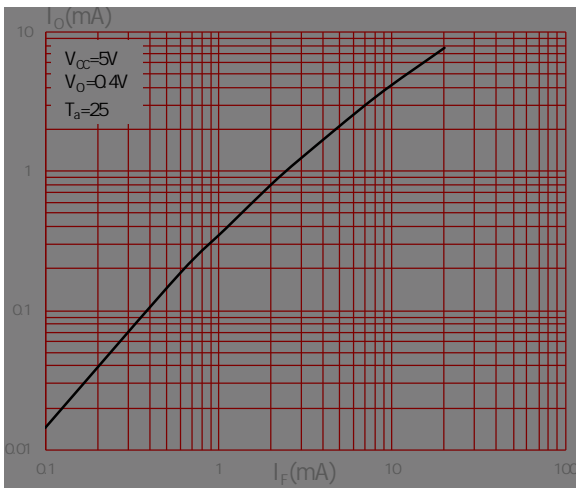


FIG.2: High Level Output Current vs. Ambient Temperature

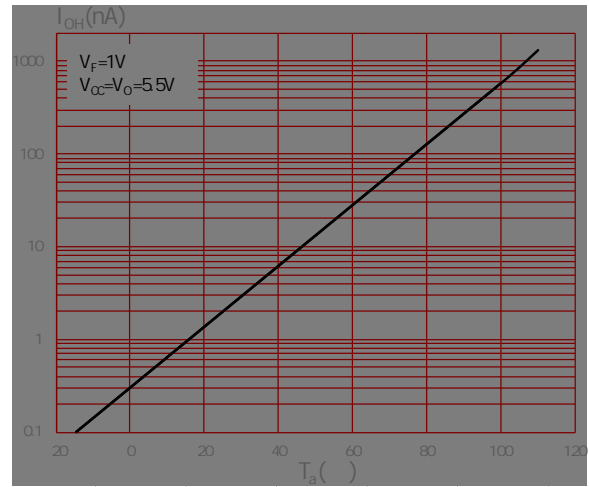


FIG.4: Threshold Input Current vs. Ambient Temperature

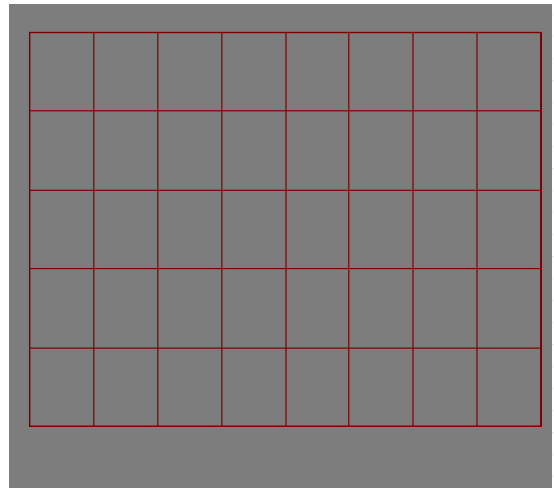


FIG.7: Propagation Delay vs. Load Resistance

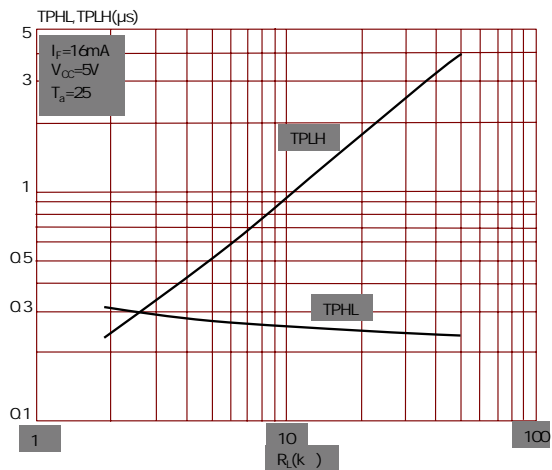
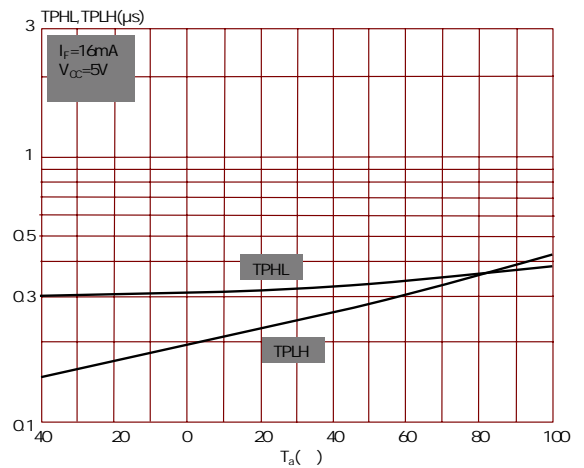


FIG.8: Propagation Delay vs. Ambient Temperature



TEST CIRCUITS

Fig.9: Switching Time Test Circuit and Waveform

$I_F=10mA(P.G.)$
 $(f=10kHz, duty=10\%, tr=tf=5ns \text{ or less})$

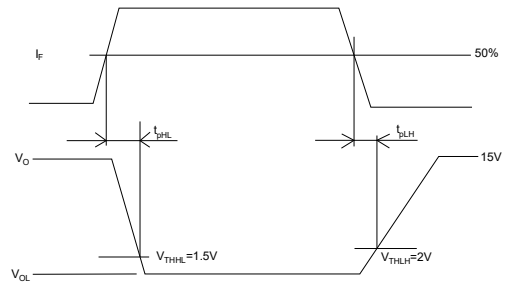
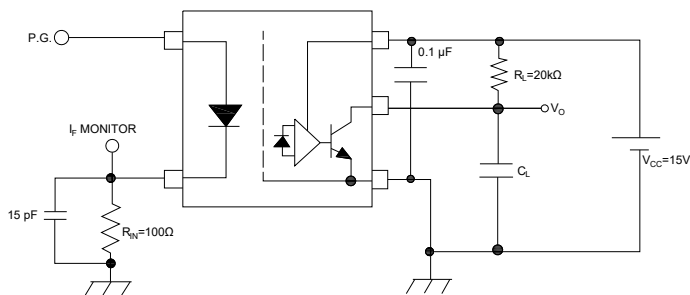
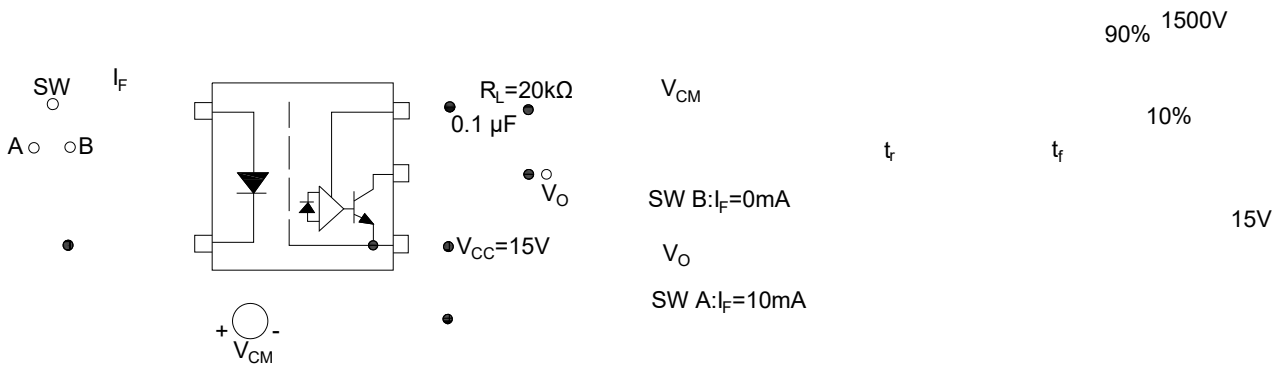
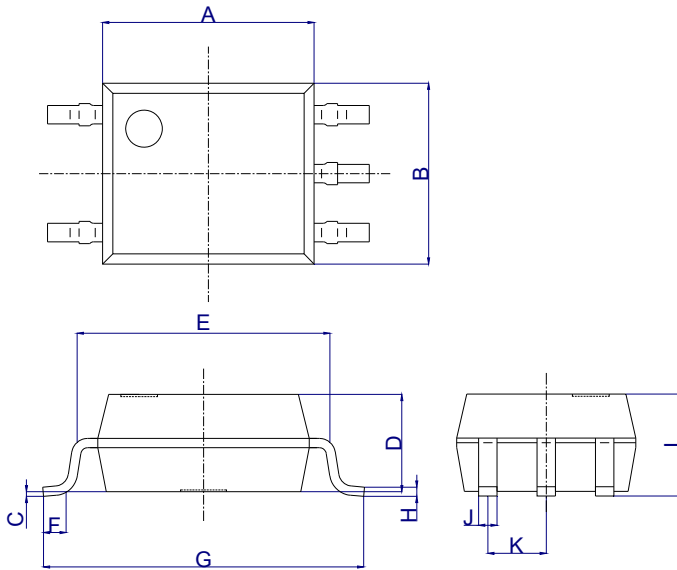


Fig.10: CMTI Test Circuit and Waveform

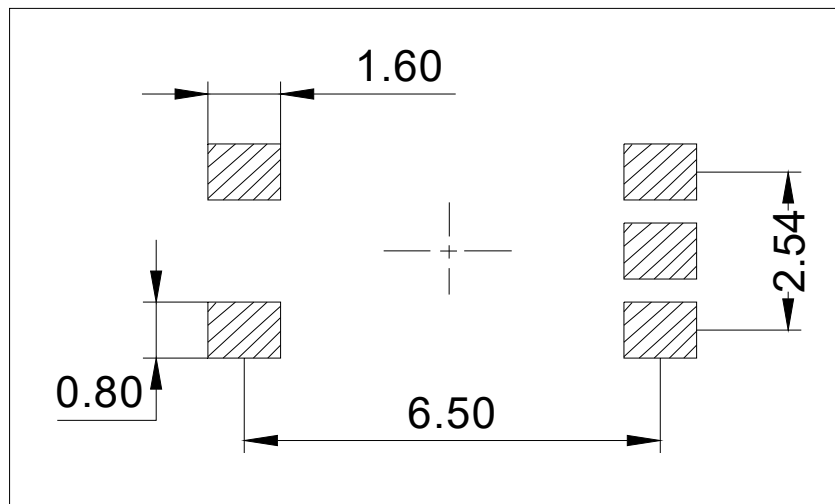


Package Dimension (Unit: mm)



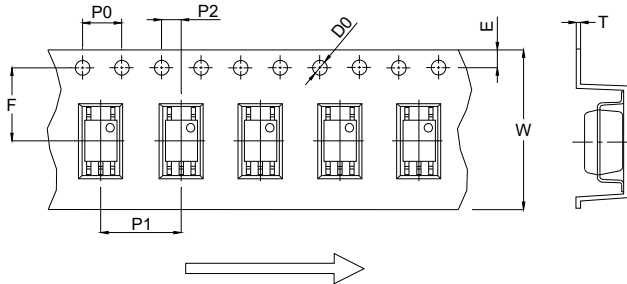
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.80	0.173		0.189
B	3.60		4.20	0.142		0.165
C	0.00		0.20	0.000		0.008
D	1.90		2.30	0.075		0.091
E	5.00		5.60	0.197		0.220
F	0.34		0.94	0.013		0.037
G	6.70		7.30	0.264		0.287
H	0.10		0.30	0.004		0.012
I	2.00		2.40	0.079		0.094
J	0.25		0.55	0.010		0.022
K	1.02		1.52	0.040		0.060

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



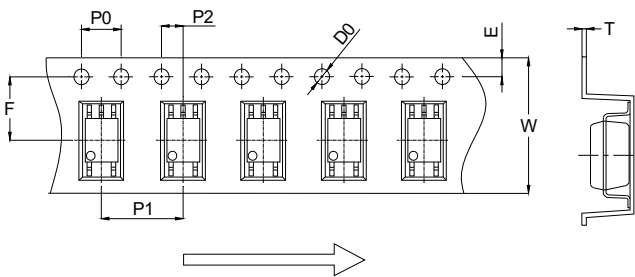
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option None



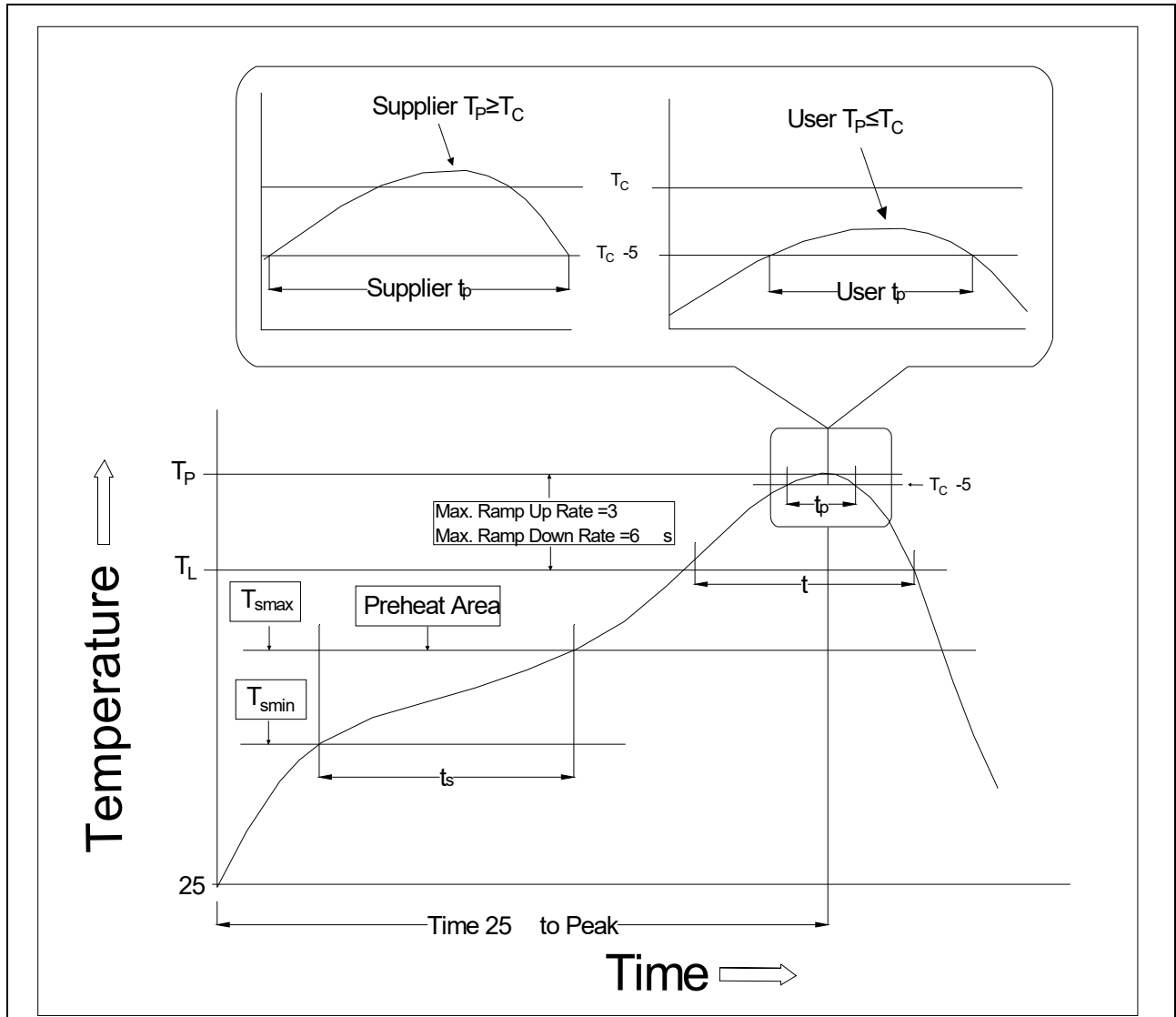
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.27	0.30	0.33	0.011	0.012	0.013
W	15.80	16.00	16.20	0.622	0.630	0.638

Option R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	4.40	4.50	4.60	0.173	0.177	0.181
T	0.25	0.30	0.35	0.010	0.012	0.014
W	11.90	12.00	12.30	0.469	0.472	0.484

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150
Temperature Max. (T _{smax})	150	200
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3 /second max.	3 /second max.
Liquidus Temperature (T _L)	183	217
Time (t _L) Maintained Above (T _L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (t _P) within 5 of 260	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6 /second max.	6 /second max.
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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